CT3061, CT3062, CT3063, CT3081, CT3082, CT3083

600V/800V Zero Cross 6-Pin DMC-Isolator® Phototriac Optocoupler

www.ct-micro.com

Features

- High isolation 5000 VRMS
- Peak Breakdown Voltage
  - 600V – CT3061, CT3062, CT3063
  - 800V – CT3081, CT3082, CT3083
- Operating Temperature range - 55 °C to 100 °C
- External Creepage ≥ 7.4mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 7.5mm (S/SL Type)
- Clearance Distance ≥ 8.0mm (M/SLM Type)
- RoHS and REACH Compliance
- Halogen Free Compliance (Optional)
- MSL class 1
- Regulatory Approvals
  - ✓ UL - UL1577 (E364000)
  - ✓ VDE - EN60747-5-5 (40039590)
  - ✓ CQC – GB4943.1, GB8898 (14001105802)
  - ✓ IEC62368 (FI/41119)

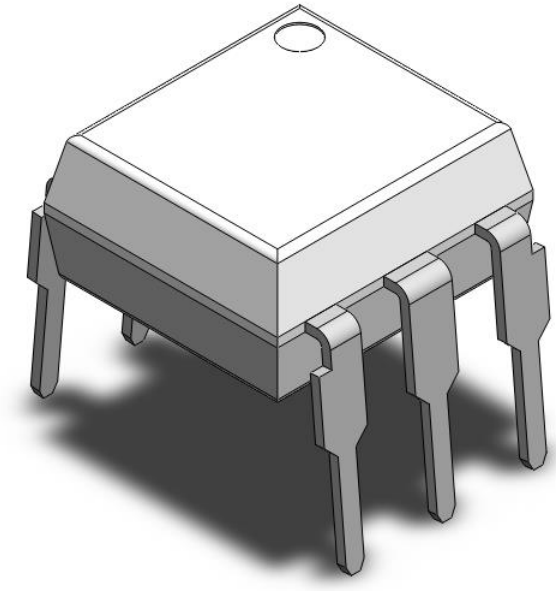
Description

The CT3061, CT3062, CT3063, CT3081, CT3082 and CT3083 series consists of a Zero Cross Photo Triac optically coupled to an Infrared-emitting diode in a 6-lead DIP DMC-Isolator® package with different lead forming options.

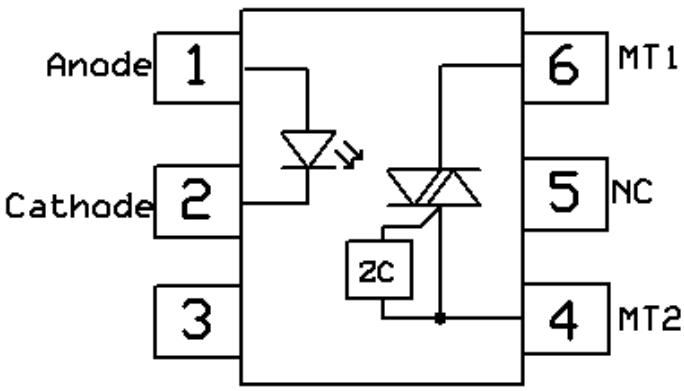
Applications

- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control

Package Outline



Schematic



Note: Different lead forming options available. See package dimension.

Absolute Maximum Ratings T_A = 25°C, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters		Ratings	Units	Notes
V_{ISO}	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)		5000	V_{RMS}	
T_{OPR}	Operating temperature		-55 ~ +100	°C	
T_{STG}	Storage temperature		-55 ~ +150	°C	
T_{SOL}	Soldering temperature (For 10 seconds)		260	°C	
Emitter					
I_F	Forward current		60	mA	
$I_{F(TRANS)}$	Peak transient current (≤1μs P.W,300pps)		1	A	
V_R	Reverse voltage		6	V	
P_D	Power dissipation		100	mW	
Detector					
P_D	Power dissipation		300	mW	
V_{DRM}	Off-State Output Terminal Voltage	CT3061,CT3062,CT3063	250	V	
		CT3081,CT3082,CT3083	400	V	
I_{TM}	RMS on-state current		100	mA	
I_{TSM}	Peak Repetitive Surge Current		1	A	
TJ	Junction temperature		<110	°C	

Electrical Characteristics T_A = 25°C, unless otherwise specified

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	I_F=10mA	-	-	1.5	V	
I_R	Reverse Current	V_R = 6V	-	-	5	μA	
C_{IN}	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

Symbol	Parameters		Test Conditions	Min	Typ	Max	Units	Notes
I_{DRM1}	Peak Blocking Current	CT3061,62,63 CT3081,82,83	I_F= 0mA, V_{DRM}= Rated V_{DRM}	-	-	500	nA	
I_{DRM2}	Inhibit Leakage Current		I_F= Rated I_{FT}, V_{DRM}= Rated V_{DRM}	-	-	500	μA	
V_{INH}	Inhibit Voltage		I_F= Rated I_{FT},	-	-	20	V	
V_{TM}	Peak On-State Voltage		I_F= Rated I_{FT}, I_{TM}= 100mA	-	-	3	V	
dv/dt	Critical Rate of Rise off-State Voltage	CT3061,62,63	V_{PEAK}= Rated V_{DRM}	1000	-	-	V/μs	
		CT3081,82,83		600	-	-		

Transfer Characteristics

Symbol	Parameters		Test Conditions	Min	Typ	Max	Units	Notes
I_{FT}	Input Trigger Current	CT3061, CT3081	Terminal Voltage = 3V I_{TM}=100mA	-	-	15	mA	
		CT3062, CT3082		-	-	10		
		CT3063, CT3083		-	-	5		
I_H	Holding Current		Terminal Voltage from “ON” to “OFF” “ON” state I_F=0mA	-	380	-	μA	
R_{IO}	Isolation Resistance		V_{IO}= 500V_{DC}	1x10^{11}	-	-	Ω	
C_{IO}	Isolation Capacitance		f= 1MHz	-	0.25	-	pF	

Typical Characteristic Curves *T_A = 25°C, unless otherwise specified*

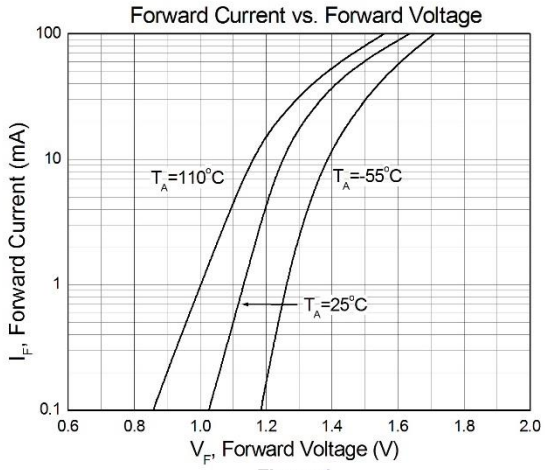


Figure 1

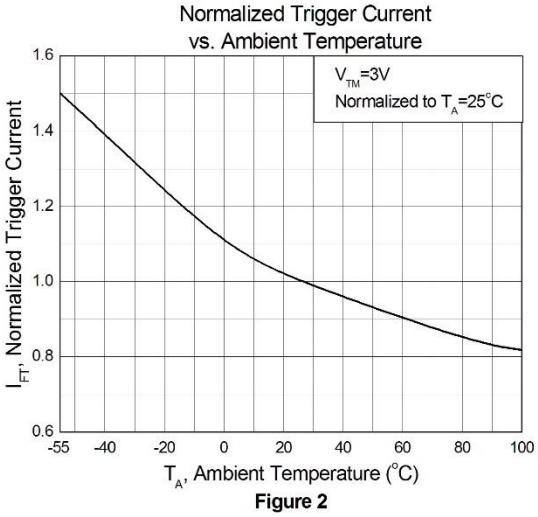


Figure 2

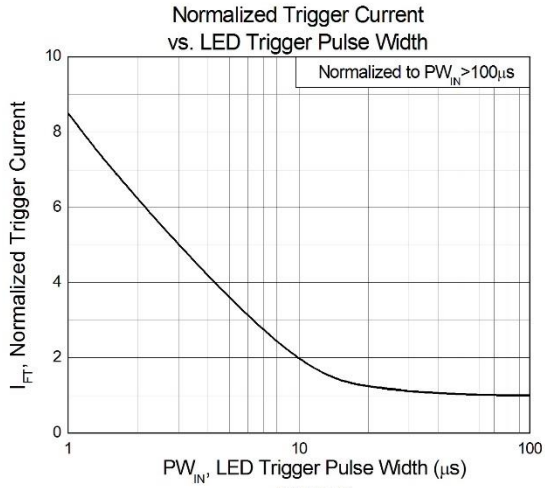


Figure 3

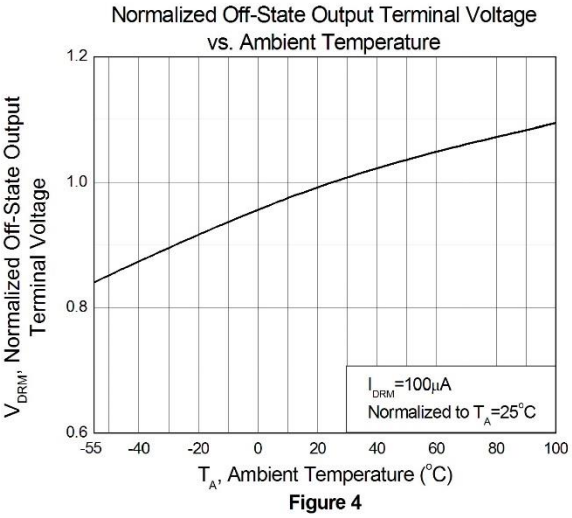


Figure 4

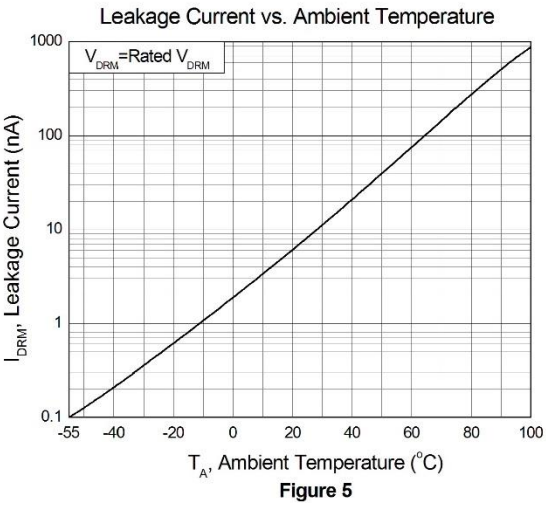


Figure 5

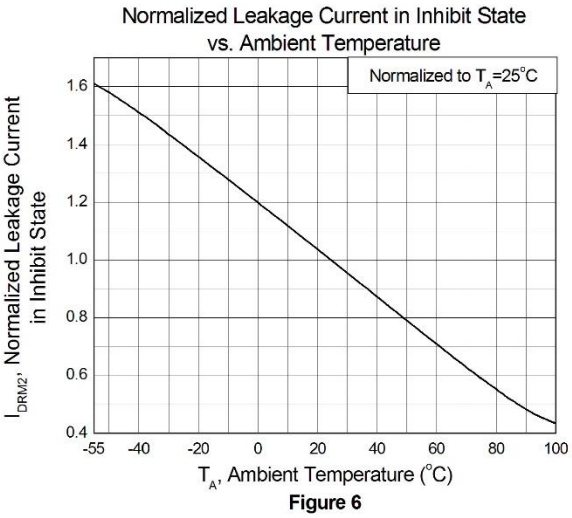


Figure 6

Typical Characteristic Curves *T_A = 25°C, unless otherwise specified (Continued)*

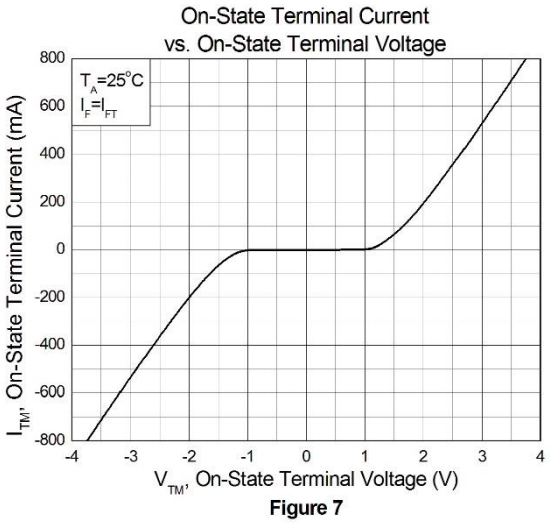


Figure 7

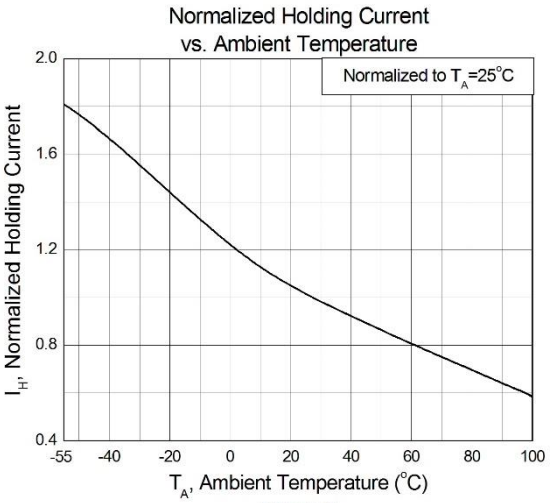


Figure 8

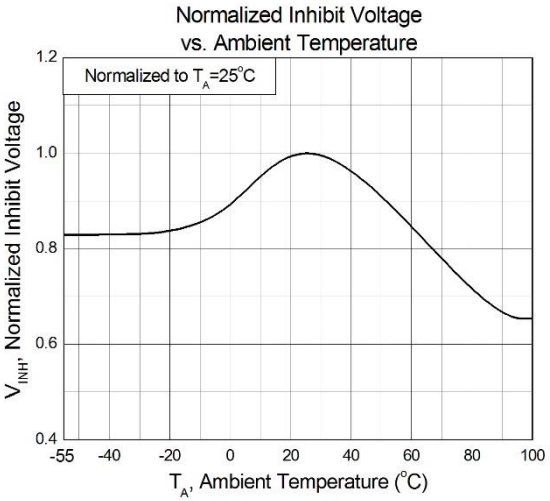
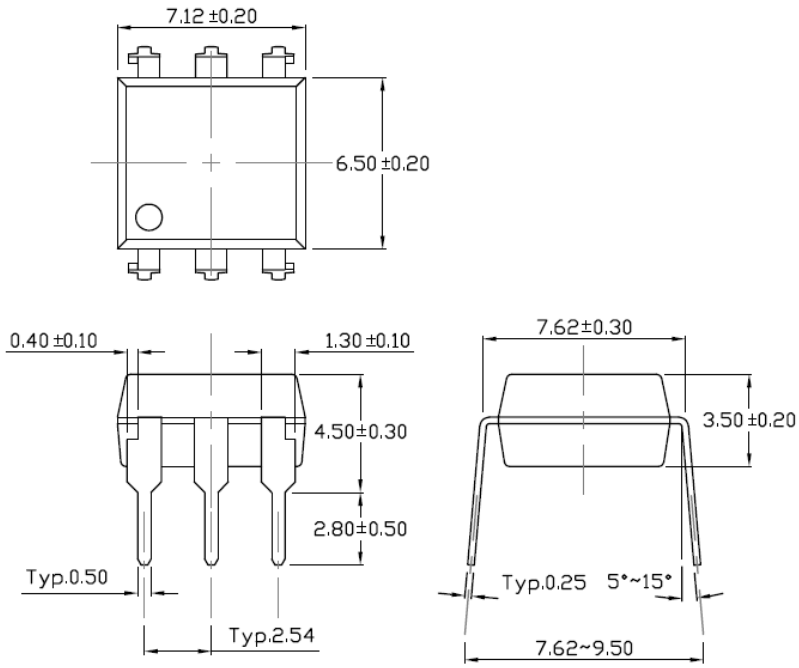
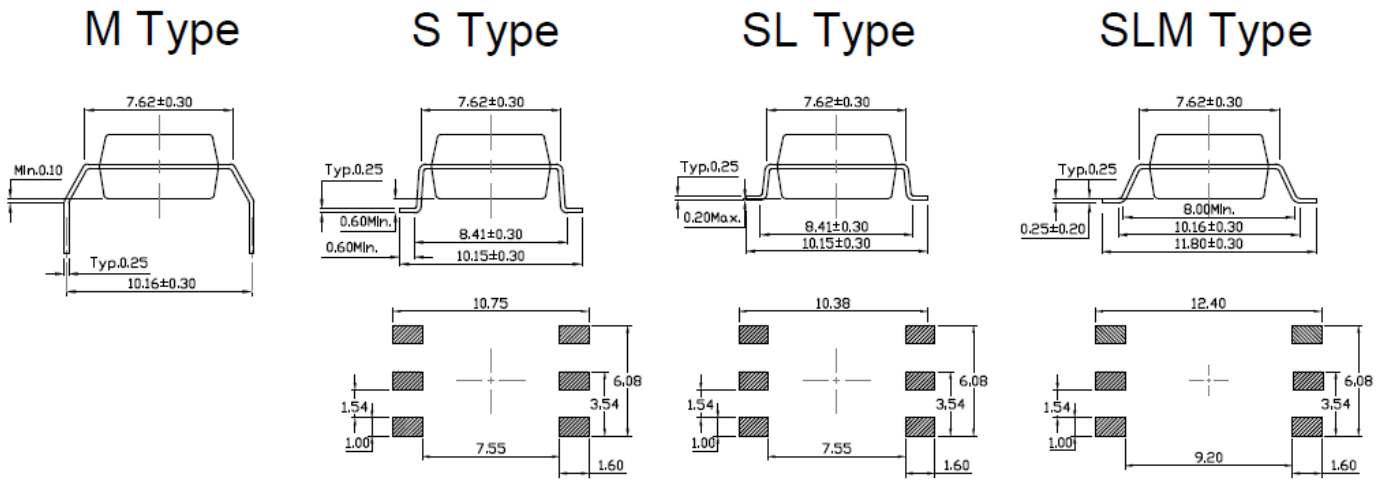


Figure 9

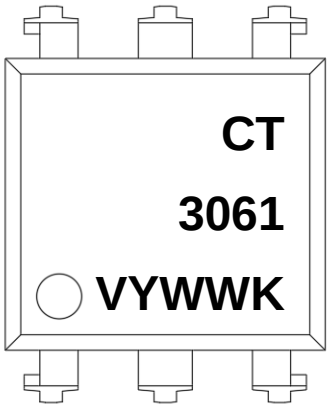
Package Dimension *Dimensions in mm unless otherwise stated*



Forming Option *Dimensions in mm unless otherwise stated*



Marking Information



Note:

CT	: Denotes “CT Micro”
3061	: Part Number
X	: CTR Rank Option (Blank, A or B)
V	: VDE Safety Mark Option (Blank or V)
Y	: One Digit Year Code
WW	: Two Digit Work Week
K	: Manufacturing Code

Ordering Information

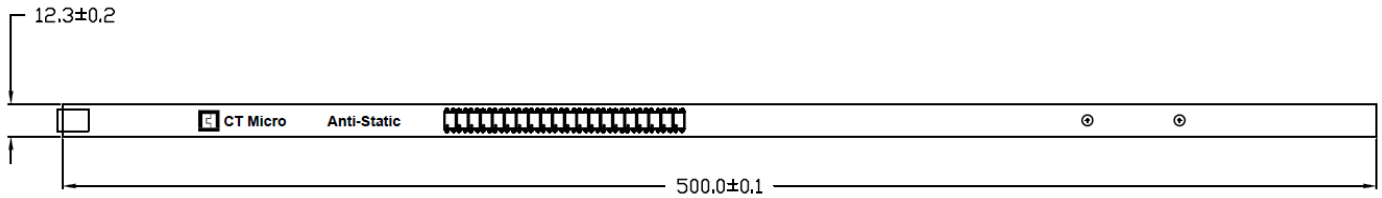
CT306X(V)(Y)(Z)-G, CT308X(V)(Y)(Z)-G

CT	= Denotes “CT Micro”
306X	= Part No. (CT306X:1,2,3), (CT308X : 1,2,3)
V	= VDE Safety Mark Option (Blank or V)
Y	= Lead Form Option (Blank, S, SL, M or SLM)
Z	= Tape and Reel Option (Blank, T1 or T2)
G	= Material Option (G: Halogen Free, Blank: Non-Halogen Free)

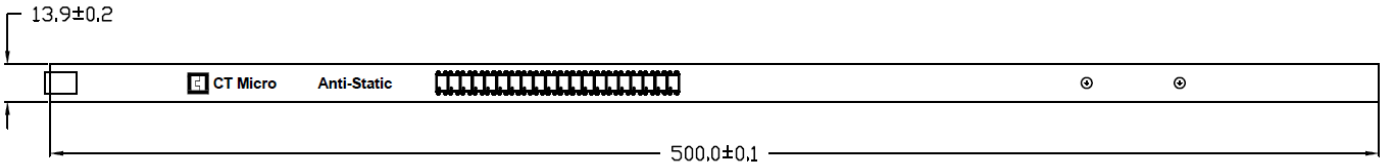
Option	*Description*	*Quantity*
None	Standard 6 Pin Dip	50Units/Tube
M	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	1000 Units/Reel
SLM(T2)	Surface Mount (Gullwing) Lead Forming – With Option 2 Taping	1000 Units/Reel

Carrier Specifications *Dimensions in mm unless otherwise stated*

Tube Option Standard DIP

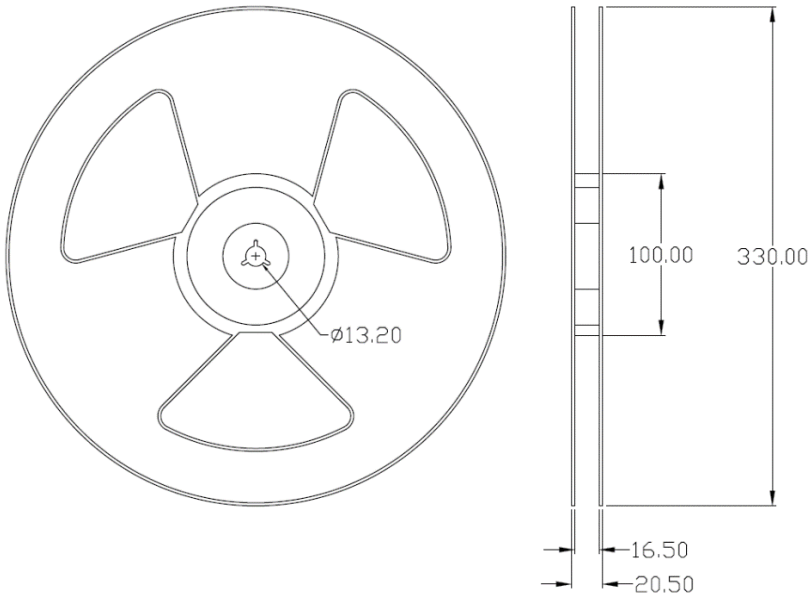


Tube Option M Type



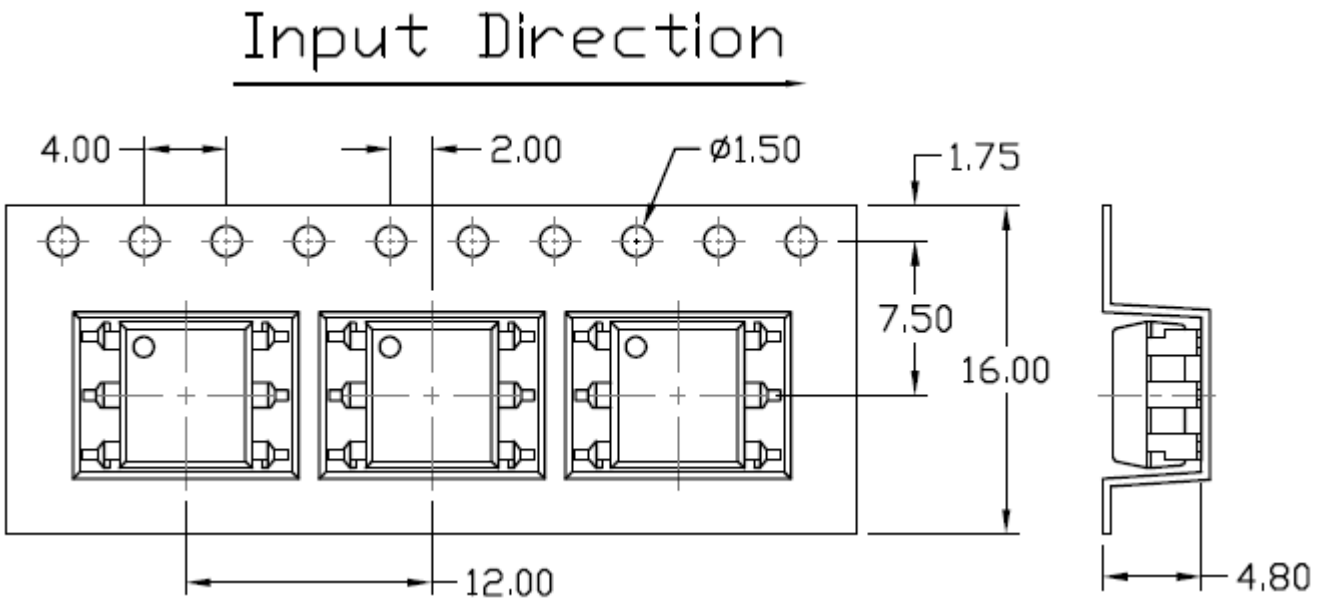
Reel Dimension *Dimensions in mm unless otherwise stated*

Option S(T1/T2) & SL(T1/T2) & SLM(T1/T2)

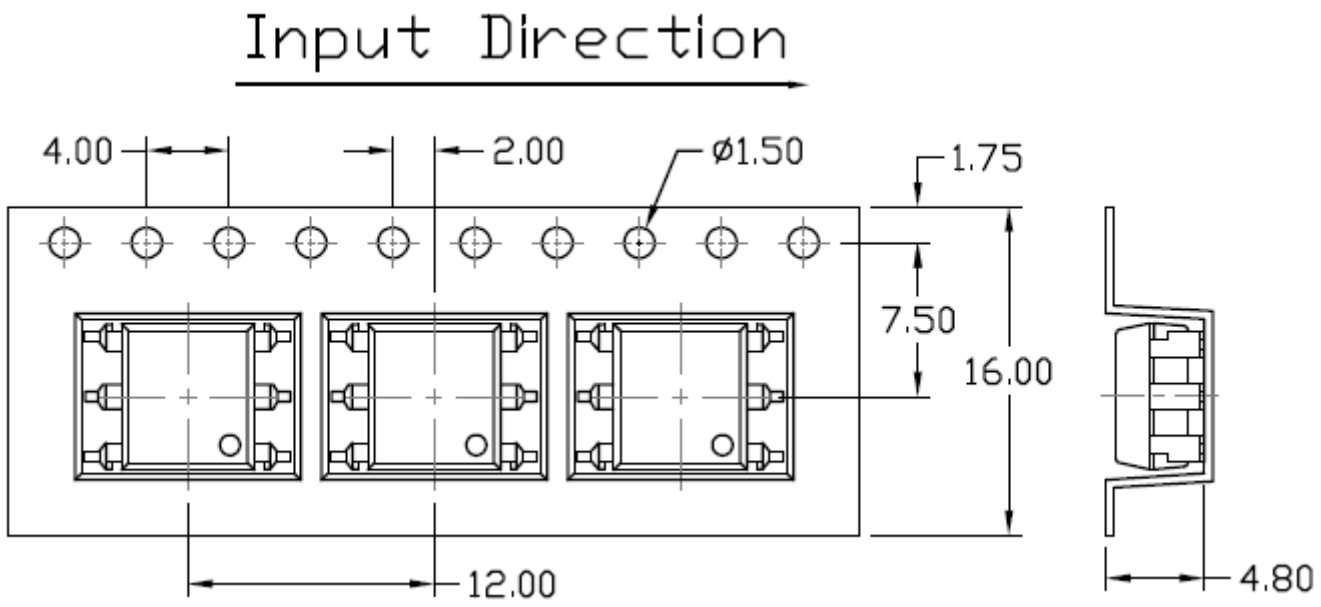


Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

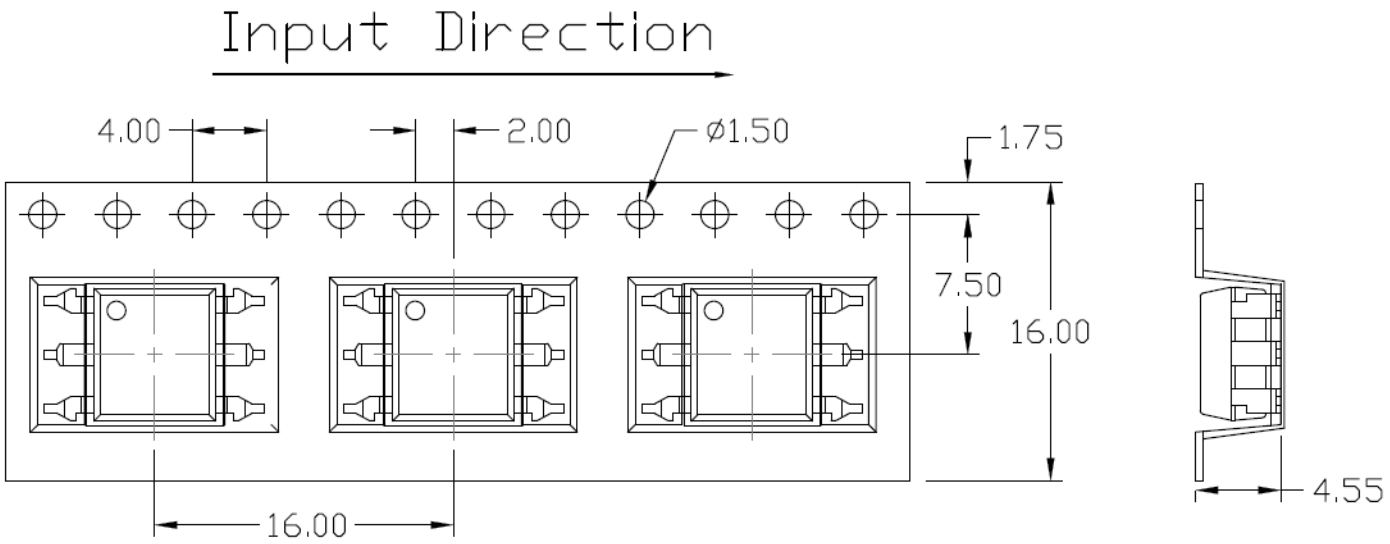
Option S(T1) & SL(T1)



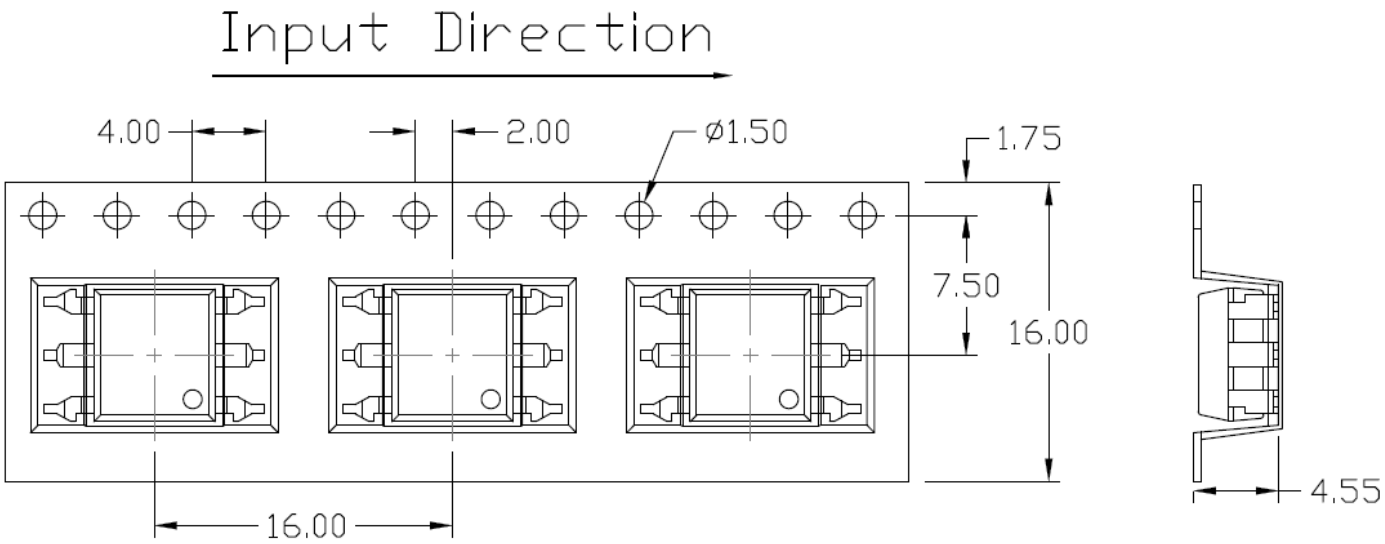
Option S(T2) & SL(T2)



Option SLM(T1)



Option SLM(T2)

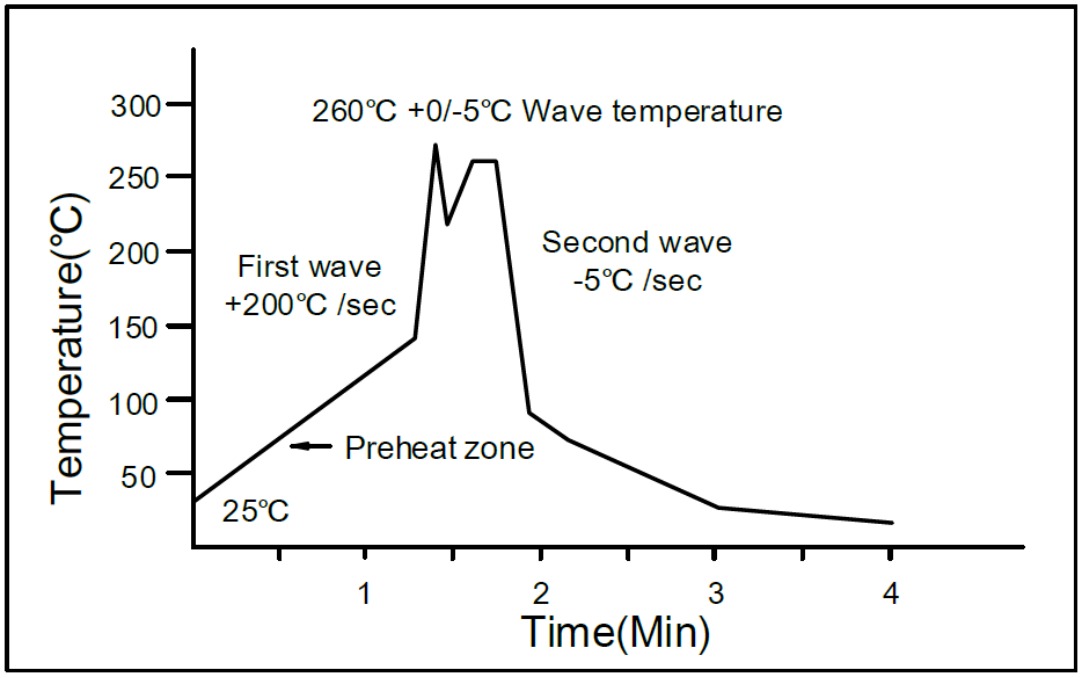


Solderability Specification (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.
Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (follow the JEDEC standard JESD22-A111)

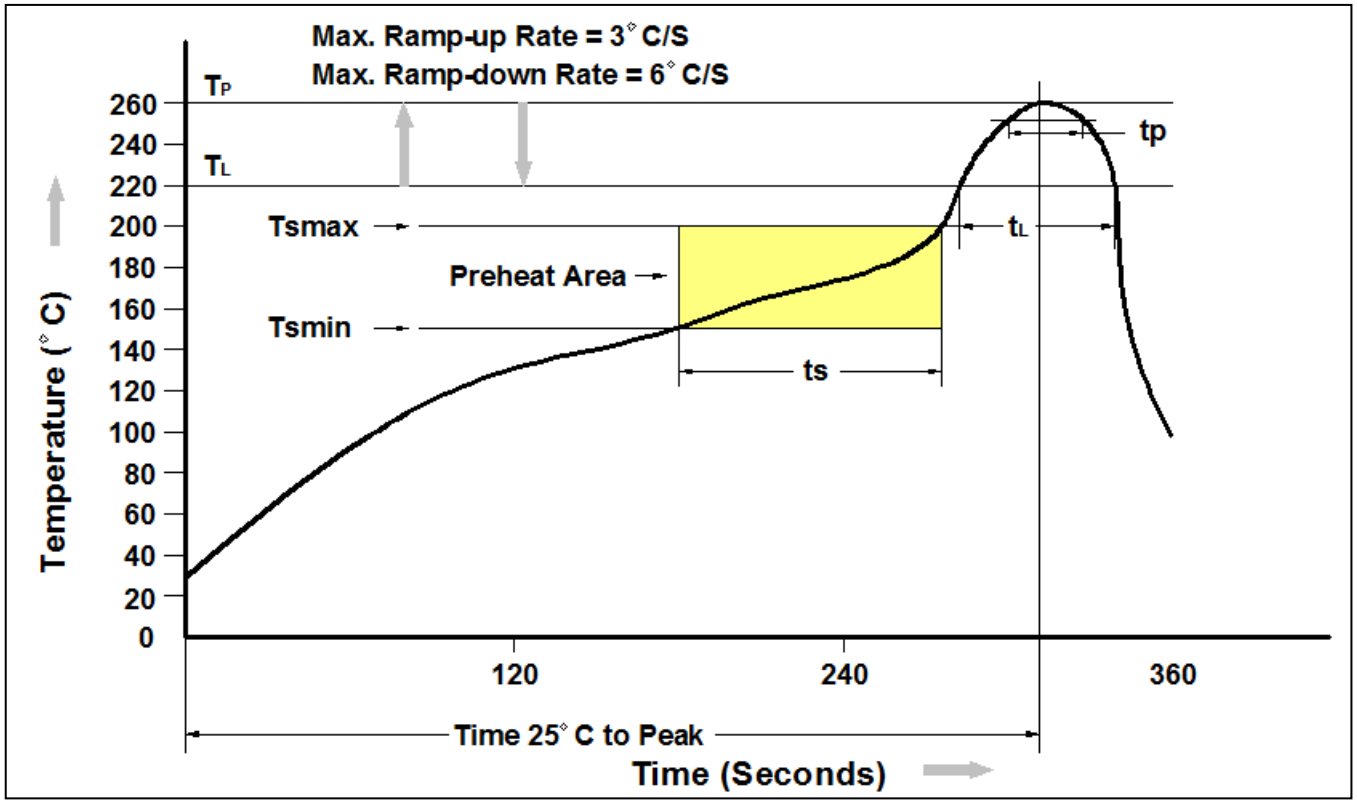
One time soldering is recommended within the condition of temperature.
Temperature: 260+0/-5˚C.
Time: 10 sec.
Preheat temperature:25 to 140˚C.
Preheat time: 30 to 80 sec.



Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.
One time soldering is recommended.
Temperature: 350±10˚C
Time: 5 sec max.

Reflow Profile (follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.
Liquidous Temperature (T_L)	217°C
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t_P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

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